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## **Certificate of Mailing**

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Date: February 9, 2004

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Sonia V. McVean

**PATENT** 50626.57

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Chun Ho FAN et al.

Serial No.: 10/661,480

Filing Date: September 15, 2003

For: METHOD OF FABRICATING A LEADLESS

PLASTIC CHIP CARRIER

Art Unit: 1765

Examiner: Unknown

# COMMENTARY RE INFORMATION DISCLOSURE STATEMENT

Mail Stop DD Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

In accordance with 37 CFR §1.56, and in recognition of their duty to disclose to the United States Patent and Trademark Office relevant information known to be material to patentability, Applicants herewith submit a copy of the Japanese prior art listed on the attached Information Disclosure Statement (Form PTO-1449), including an English abstract. Applicants did not submit a copy of the U.S. prior art references, as it is no longer a requirement.

The statement is not a representation that all of the information cited is necessarily effective as prior art against the application.

U.S. Application No. 10/661,480 February 9, 2004 Page 2 of 2

Applicants respectfully request that the disclosed reference be made of record in the subject application.

Respectfully submitted,

Date: February 9, 2004

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ATTY. DOCKET NO.

50626.57

Sheet <u>1</u> of _	
SERIAL NO. 10/661,480	

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

U.S. DEPARTMENT OF COMMERCE

PATENT AND TRADEMARK OFFICE

APPLICANTS: Chun Ho FAN et al.

FILING DATE GROUP
September 15, 2003 1765

### **U.S. PATENT DOCUMENTS**

*INITIAL	DOCUMENT NO.	DATE	NAME	CLASS	SUBCL.	FILING DATE
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### **FOREIGN PATENT DOCUMENTS**

	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCL.	TRANSLATION	
	JP 59-208756	11/1984				YES	NO
							·
OTHER DOCUME	NTS (Including Author,	Title, Date, Pertiner	nt Pages, Etc.)		-		
			-				·
<del></del>			DATE CONSIDERED:				

<sup>\*</sup>EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if in conformance and not considered. Include copy of this form with next communication with applicant.